

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No. 10/053,555

7. (Amended) A junction flexible wiring circuit board according to Claim 1, wherein said metal layer is formed at least on a side of said junction flexible wiring circuit board on which the terminal portions connected to said suspension board are provided.

Please add the following new claims:

9. (New) A junction flexible wiring circuit board provided in combination with a suspension board for mounting a magnetic head thereon and a control circuit board for operating said magnetic head, comprising:

a metal layer formed as a front surface layer of said junction flexible wiring circuit board; and

a characteristic impedance of said junction flexible wiring circuit board being within \pm 10% of a characteristic impedance of said suspension board and within \pm 10% of a characteristic impedance of said control circuit board.

10. (New) A junction flexible wiring circuit board provided in combination with a suspension board and a control circuit board according to claim 9, wherein the metal layer is disposed on the junction flexible wiring circuit board in a same manner as a metal layer disposed on the suspension board so that the characteristic impedance of the junction flexible wiring circuit board and the suspension board are substantially equal.

11. (New) dependent A junction flexible wiring circuit board according to claim 1, wherein a thickness of the metal layer is in a range from 100 angstroms to 50 μm .

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12. (New) A junction flexible wiring circuit board according to claim 1, wherein a thickness of the metal layer is in a range from 500 angstroms to 30 μm .

13. (New) A junction flexible wiring circuit board according to claim 7, wherein said metal layer is formed on both sides of said junction flexible wiring circuit board.